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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of:

Li et al.

Serial No.: 10/759,448

Filed: 01/16/2004

SPIN-ON PROTECTIVE COATINGS FOR
WET-ETCH PROCESSING OF
MICROELECTRONIC SUBSTRATES

Docket No.: 34393

Group Art Unit No.:

Examiner:

TRANSMITTAL

Transmitted herewith are: Transmittal; Information Disclosure Statement; Information Disclosure Statement by Applicant (PTO-1449) with cited references; and return postcard.

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Express Mail No.

Respectfully submitted,

HOVEY WILLIAMS LLP

Dated: April 23, 2004

by

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ATTORNEYS FOR APPLICANT



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Assistant Commissioner of Patents
Washington, D.C. 20231

Sir:

INFORMATION DISCLOSURE STATEMENT

The attached references are being filed to fulfill the duty of candor and good faith toward the
Patent and Trademark Office, as required by 37 C.F.R. §1.56.

Respectfully submitted,

By

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FORM PTO-1449
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PATENT AND TRADEMARK OFFICEATTY. DOCKET NO.
34393SERIAL NO.
10/759,448INFORMATION DISCLOSURE
STATEMENT BY APPLICANT

APPLICANT: Li et al.

FILING DATE:
01-16-2004

GROUP:

(Use several sheets if necessary)

U.S. PATENT DOCUMENTS

EXAM. INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	5 7 5 3 5 2 3	May 19, 1998	Giedd et al.			

FOREIGN PATENT DOCUMENTS

DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION
					YES NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

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EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.